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Docket No.: 075905-0038



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Documents or the new address(es) below.

To the Director of the U. S. Patent and Trademark Office

1. Name of Conveying Party(ies)

Takashi GOMI, Ryoji INABA, Motohiro YAMAZAKI,
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Name: HITACHI HIGH-TECHNOLOGIES
CORPORATION

Address of receiving party(ies)

Internal Address:

Additional name(s) of conveying party(ies) attached? Yes No

3. Nature of Conveyance/Execution Date(s)

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(Respectively)

Address: 1-24-14, Nishi Shimbashi, Minato-ku,
Tokyo, Japan

- Assignment Merger
 Security Agreement Change of Name
 Joint Research Agreement
 Government Interest Assignment
 Executive Order 9424, Confirmatory License
 Other

Additional name(s) & address(es) attached? Yes No

4. Application or patent number(s):

A. Patent Application No(s).

This document is being filed together with a new application

B. Patent No(s).

Additional numbers attached? Yes No

5. Name and address to whom correspondence concerning document should be mailed:

6. Total number of applications and patents involved: 1

Name: MCDERMOTT WILL & EMERY LLP

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7. Total fee (37 CFR 1.21(h) & 3.41) \$40.00

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 None required (government interest not affecting title)

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9. Signature.

Keith E. George, 34,111

June 5, 2007

Name and Registration No. of Person Signing

Signature

Date

Total number of pages including cover sheet, attachments and documents: 2

OMB No. 0651-0027 (exp. 6/30/2008)

PATENT
REEL: 019434 FRAME: 0925

ASSIGNMENT

(譲 渡 証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Hitachi High-Technologies Corporation, a corporation organized under the laws of Japan, located at 1-24-14, Nishi Shimbashi, Minato-ku, Tokyo, Japan receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi High-Technologies Corporation, its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

CAPILLARY ELECTROPHORESIS APPARATUS

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Hitachi High-Technologies Corporation, its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi High-Technologies Corporation,

Signed on the date(s) indicated aside our signatures:

INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
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10) _____	_____